In order to remove, after treatment of wafer-shaped articles (2), preferably a silicon wafer, with a treatment medium, preferably with an etching fluid, on the bottom of wafer-shaped article (2), i.e. the side facing chuck (1) for wafer-shaped article (2), residual treatment medium adhering in its edge area, there is nozzle (20) from which flushing liquid, preferably deionized water, can be sprayed onto the outside edge of article (2) and between chuck (1) and wafer-shaped article (2). The flushing liquid, which penetrates more or less deeply, depending on the pressure with which the flushing liquid emerges from nozzle (20) and depending on the alignment of nozzle (20) relative to wafer-shaped article (2), is flung off again by the rotation of wafer-shaped article (2) and in doing so entrains residues of treatment medium. For optimum action the alignment of nozzle (20) can be changed relative to edge (16) of wafer-shaped article (2).

8 Claims, 2 Drawing Sheets